



Product Change Notification

Change Notification #: 117699 - 01
Change Title: Intel® Server Chassis Hot Swap Drive Kit FUP4X35S3HSDK,
Intel® Server Chassis Hot Swap Drive Kit FUP8X25S3HSDK,
Intel® Bracket and Extension Kit AUPMCOPROBR,
PCN 117699-01, Product Discontinuance, End of Life,
Reason for Revision: Adding Intel® Bracket and Extension Kit AUPMCOPROBR.

Date of Publication: August 12, 2020

Key Characteristics of the Change:

Product Discontinuance

Forecasted Key Milestones:

Product Discontinuance Program Support Begins:	July 20, 2020
Last Product Discontinuance Order Date:	August 20, 2020
Orders are Non-Cancelable and Non-Returnable After:	August 20, 2020
Last Product Discontinuance Shipment Date:	October 20, 2020

Description of Change to the Customer:

Reason for Revision: Adding Intel® Bracket and Extension Kit AUPMCOPROBR.

Intel is announcing the discontinuance of the Intel® Server Chassis Hot Swap Drive Kits listed in the "Products Affected/Intel Ordering Codes" table below.

Intel will make best efforts to support all orders placed between the Non-Cancelable and Non-Returnable (NCNR) and the Last Product Discontinuance Order (LPDO) dates. Intel will discontinue builds on the LPDO date. After the LPDO date existing inventory is still orderable, under NCNR terms, and will be filled on a first come first served basis. Deliveries must be accepted within 60 days from the LPDO date.

Final purchase orders are non-cancelable and non-returnable, notwithstanding any conflicting terms in our quotes, purchase order acknowledgement or Distributor agreements.

Intel reserves the right to change the products because of material source restriction.

Engineering and Support Guidance for Discontinued Products:

1. No new OS, peripheral or adaptor validation is planned during the extended life period. The THOL, supported processor and tested memory lists are frozen at PDA.
2. No new features enhancements should be expected, however ECOs may be required during the extended life period to maintain supply lines (e.g. to qualify new vendor due to a component EOL).
3. Intel will provide reasonable commercial efforts in debugging issues during the warranty period for the product after the PDA date has passed. Fixes cannot be committed, but Intel will endeavor to provide reasonable workarounds for the product.

Customer Impact of Change and Recommended Action:

Determine your remaining demand for this product and/or evaluate additional sources (if applicable).

Lead-times on products with announced product discontinuance can typically stretch to 12 weeks and volumes are not buffered during the PDA period. Please work with your Intel representative on your quarterly demand forecast in order to reduce lead-times to 2-4 Weeks.

Please contact your local Intel Sales Office or Distributor if you require more information or need assistance in selecting a replacement product.

Milestone dates are estimates and subject to change based on business and operational conditions.

Products Affected / Intel Ordering Codes:

Marketing Name	Product Code	MM#
8x2.5in Hot-swap Drive Cage Kit FUP8X25S	FUP8X25S3HSDK	936425
3.5in Hot-swap Drive Cage Kit for P4000	FUP4X35S3HSDK	936623
Bracket and Extension	AUPMCOPROBR	926364

PCN Revision History:

Date of Revision:

July 20, 2020

[August 12, 2020](#)

Revision Number:

00

[01](#)

Reason:

Originally Published PCN

[Adding Intel® Bracket and Extension Kit AUPMCOPROBR.](#)



Product Change Notification

117699 - 01

INFORMATION IN THIS DOCUMENT IS PROVIDED IN CONNECTION WITH INTEL PRODUCTS. NO LICENSE, EXPRESS OR IMPLIED, BY ESTOPPEL OR OTHERWISE, TO ANY INTELLECTUAL PROPERTY RIGHTS IS GRANTED BY THIS DOCUMENT. EXCEPT AS PROVIDED IN INTEL'S TERMS AND CONDITIONS OF SALE FOR SUCH PRODUCTS, INTEL ASSUMES NO LIABILITY WHATSOEVER AND INTEL DISCLAIMS ANY EXPRESS OR IMPLIED WARRANTY, RELATING TO SALE AND/OR USE OF INTEL PRODUCTS INCLUDING LIABILITY OR WARRANTIES RELATING TO FITNESS FOR A PARTICULAR PURPOSE, MERCHANTABILITY, OR INFRINGEMENT OF ANY PATENT, COPYRIGHT OR OTHER INTELLECTUAL PROPERTY RIGHT.

A "Mission Critical Application" is any application in which failure of the Intel Product could result, directly or indirectly, in personal injury or death. SHOULD YOU PURCHASE OR USE INTEL'S PRODUCTS FOR ANY SUCH MISSION CRITICAL APPLICATION, YOU SHALL INDEMNIFY AND HOLD INTEL AND ITS SUBSIDIARIES, SUBCONTRACTORS AND AFFILIATES, AND THE DIRECTORS, OFFICERS, AND EMPLOYEES OF EACH, HARMLESS AGAINST ALL CLAIMS COSTS, DAMAGES, AND EXPENSES AND REASONABLE ATTORNEYS' FEES ARISING OUT OF, DIRECTLY OR INDIRECTLY, ANY CLAIM OF PRODUCT LIABILITY, PERSONAL INJURY, OR DEATH ARISING IN ANY WAY OUT OF SUCH MISSION CRITICAL APPLICATION, WHETHER OR NOT INTEL OR ITS SUBCONTRACTOR WAS NEGLIGENT IN THE DESIGN, MANUFACTURE, OR WARNING OF THE INTEL PRODUCT OR ANY OF ITS PARTS.

Intel may make changes to specifications and product descriptions at any time, without notice. Designers must not rely on the absence or characteristics of any features or instructions marked "reserved" or "undefined". Intel reserves these for future definition and shall have no responsibility whatsoever for conflicts or incompatibilities arising from future changes to them. The information here is subject to change without notice. Do not finalize a design with this information.

The products described in this document may contain design defects or errors known as errata which may cause the product to deviate from published specifications. Current characterized errata are available on request.

Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com

Asia Pacific/PRC Contact: apacgccb@intel.com

Europe Email: eccb@intel.com

Japan Email: jccb.ijkk@intel.com

Copyright © Intel Corporation 2020. Other names and brands may be claimed as the property of others.

3D XPoint, ACEX, Altera, APEX, AnyWAN, Arria, Avalon, Axxia, BlueMoon, BunnyPeople, Celeron, Centrino, Cilk, CONVERGATE, Cyclone, Docea, eASIC, easicopy, Enpirion, Flexpipe, Hyperflex, Intel, the Intel logo, Intel Adaptix, Intel Agilix, Intel Atom, Intel CoFluent, Intel Core, Intel. Experience What's Inside, the Intel. Experience What's Inside logo, Intel Falcon, Intel Inside, the Intel Inside logo, Intel Nervana, Intel Optane, Intel RealSense, Intel Shooting Star, Intel Sirius, Intel SpeedStep, Intel Unite, Intel vPro, Intel Xeon Phi, Iris, Itanium, MAX, Movidius, Myriad, neon, Nios, OpenVINO, the OpenVINO logo, Pentium, Puma, Quark, Quartus, SICOFI, Simics, SMARTi, SoftSilicon, Sound Mark, StarPro, Stratix, the Stratix logo, Stay With It, the Engineering Stay With It logo, StreamSight, Tarari, The Journey Inside, Thunderbolt, the Thunderbolt logo, Transcede, Ultrabook, VTune, Xeon, X-GOLD, XMM, X-PMU and XPOSYS are trademarks of Intel Corporation or its subsidiaries in the U.S. and/or other countries.

Microsoft, Windows, and the Windows logo are trademarks, or registered trademarks of Microsoft Corporation in the United States and/or other countries. Java is a registered trademark of Oracle and/or its affiliates. Bluetooth is a trademark owned by its proprietor and used by Intel Corporation under license. Intel Corporation uses the Palm OS* Ready mark under license from Palm, Inc. OpenCL and the OpenCL logo are trademarks of Apple Inc. used by permission by Khronos. Learn how to use Intel Trademarks and Brands correctly at <http://www.intel.com/intel/legal/tmusage2.htm>.